REMARKS

This is in full and timely response the non-final Office Action dated February 14, 2003. Reexamination in light of the amendments and the following remarks is respectfully requested.

Claims 1-25 are currently pending in this application, with claims 1-7 being independent. Claims 3-7 have been withdrawn from consideration by the Examiner.

No new matter has been added.

Rejection Under 35 U.S.C. §102 and §103

Claims 1, 12-15 were rejected under 35 U.S.C. 102 as allegedly being anticipated by U.S. Patent No. 3,910,806 to Schwartz.

Claims 1 and 8-10 were rejected under 35 U.S.C. 102 as allegedly being anticipated by Japanese Publication No. 01-167933 to Yuzo.

Claim 11 was rejected under 35 U.S.C. 103 as allegedly being obvious over Schwartz in view of U.S. Patent No. 5,418,075 to Utsumi.

Claims 2, 19-20 were rejected under 35 U.S.C. 103 as allegedly being obvious over Schwartz in view of U.S. Patent No. 5,141,461 to Nishimura et al. (Nishimura).

Claims 2, 16-18 were rejected under 35 U.S.C. 103 as allegedly being obvious over Yuzo in view of Nishimura.

Claim 21 was rejected under 35 U.S.C. 103 as allegedly being obvious over Schwartz in view of Nishimura in further view of Utsumi.

These rejections are respectfully traversed for at least the following reasons.

As an initial matter, while not conceding the propriety of the rejection and in order to advance prosecution, the features of claim 10 have been incorporated into claim 1 to form amended claim 1 along with the cancellation of claim 10, the features of claim 18 have been incorporated into claim 2 to form amended claim 2 along with the cancellation of claim 18.

Within the claims, the adhesion layer is between the conducting film layer and a cover film. The specification as originally filed depicts cover film 5 (figures 1,2).

Schwartz arguably depicts and adhesive 16 and a cathode ray faceplate 18 (figure 3), but fails to disclose, teach or suggest a cover film.

Yuzo arguably depicts and adhesive 6 and a cathode ray tube 8 (abstract figure), but fails to disclose, teach or suggest a cover film.

Utsumi arguably depicts and adhesive 11 (figure 2) and a cathode ray tube 1 (figure 4B), but fails to disclose, teach or suggest a cover film.

Nishimura arguably depicts and adhesive 6 and a glass board 9, but fails to disclose, teach or suggest a cover film.

Accordingly, if the allowance of the claims is not forthcoming at the very least, then a **new non-final Office Action** is respectfully requested.

Withdrawal of these rejections and allowance of the claims is respectfully requested.

Conclusion

For the foregoing reasons, all the claims now pending in the

present application are allowable, and the present application is in condition for allowance. Accordingly, favorable reexamination and reconsideration of the application in light of the amendments and remarks is courteously solicited.

If the Examiner has any comments or suggestions that could place this application in even better form, the Examiner is requested to telephone Brian K. Dutton, Reg. No. 47,255, at 202-955-8753, or the undersigned attorney. If any fee is required, the Commissioner is hereby authorized to charge the fee to Deposit Account # 18-0013.

Respectfully submitted,

DATE: May 13, 2003

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APPENDIX

IN THE CLAIMS

Please cancel claims 10, 18 without prejudice or disclaimer of their underlying subject matter.

Please amend the claims as follows.

1. (amended) A transfer film comprising:

a base film,

a conducting film layer formed on said base film, and

an adhesion layer formed on said conducting film layer,

wherein said adhesion layer is between said conducting film layer and a cover film.

2. (amended) A transfer film comprising:

a base film,

a heat absorption film layer formed on said base film,

a conducting film layer formed on said heat absorption film layer, and

an adhesion layer formed on said conducting film layer,

wherein said adhesion layer is between said conducting film layer and a cover film.

3. A method for fabricating a thin film for a display apparatus panel, comprising the steps of:

disposing a transfer film on said display apparatus panel, said transfer film being constructed by forming a conducting film layer on a base film and an adhesion layer on said conducting film layer, and

heating and pressing said transfer film onto said display apparatus panel to transfer said conducting film layer to said display apparatus panel.

4. A method for fabricating a thin film for a display apparatus panel, comprising the steps of:

disposing a transfer film on said display apparatus panel, said transfer film being constructed by forming a heat absorption film layer on a base film, a conducting film layer on said heat absorption film layer, and an adhesion layer on said conducting film layer, and

heating and pressing said transfer film onto said display apparatus panel to transfer said heat absorption film layer and said conducting film layer to said display apparatus panel.

5. A display apparatus comprising:

a conducting film fabricated by transferring from a transfer film comprising a base film,

a conducting film layer formed on said base film layer, and an adhesion layer formed on said conducting film layer.

6. A display apparatus comprising:

a conducting film and a heat absorption film fabricated by transferring from a transfer film comprising a base film, a heat absorption film layer formed on said base film, a conducting film layer formed on said heat absorption film layer, and an adhesion layer formed on said conducting film layer.

7. A method for fabricating a film for a display apparatus panel, comprising the steps of:

disposing a transfer film on said display apparatus panel, said transfer film having said film to be attached on said display apparatus panel, and

heating and pressing said transfer film onto said display apparatus panel.

8. The transfer film of claim 1, further comprising:

a cushion film formed between said base film and said conducting film layer, the adhesiveness of said cushion film to said base film being stronger than the adhesiveness of said cushion film to said conducting film layer.

9. The transfer film of claim 8, wherein said cushion film is in contact with said base film.

10. (canceled).

11. The transfer film of claim 1, wherein said base film consists essentially of polyethylene terephthalate (PET).

12. The transfer film of claim 1, wherein said conducting film layer is a metal back film.

13. The transfer film of claim 1, wherein said conducting film layer is composed of aluminum.

14. The transfer film of claim 1, wherein said adhesion layer is in contact with said conducting film layer.

15. The transfer film of claim 1, wherein said adhesion layer is adapted for adherence to an inside surface of a cathode ray tube.

16. The transfer film of claim 2, further comprising:

a cushion film formed between said base film and said heat absorption film layer, the adhesiveness of said cushion film to said base film being stronger than the adhesiveness of said cushion film to said heat absorption film layer.

17. The transfer film of claim 16, wherein said cushion film is in contact with said base film.

18. (canceled).

19. The transfer film of claim 2, wherein said heat absorption film layer, when disposed onto a cathode ray tube, absorbs heat from an aperture grille.

20. The transfer film of claim 2, wherein said heat absorption film layer composed of a black color film of graphite.

21. The transfer film of claim 2, wherein said base film consists essentially of polyethylene terephthalate (PET).

22. The transfer film of claim 2, wherein said conducting film layer is a metal back film.

23. The transfer film of claim 2, wherein said conducting film layer is composed of aluminum.

24. The transfer film of claim 2, wherein said adhesion layer is in contact with said conducting film layer.

25. The transfer film of claim 2, wherein said adhesion layer is adapted for adherence to an inside surface of a cathode ray tube.